AiT Semiconductor Inc.

## DESCRIPTION

The MDL6050 is available in SOD-323 Package

## ORDERING INFORMATION

| Package Type | Part Number |
| :---: | :---: |
| SOD-323 | MDL6050 |
| Note | 3,000 pcs/Reel |
| AiT provides all RoHS Compliant Products |  |

## FEATURES

- RoHS Compliant
- Available in SOD-323 Package


## PIN DESCRIPTION



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## ABSOLUTE MAXIMUM RATINGS

| $V_{R}$, Reverse Voltage | 70 Vdc |
| :--- | ---: |
| $\mathrm{I}_{\mathrm{F}}$, Forward Current | 200 mAdc |
| $\mathrm{I}_{\text {FM(surge }), ~ P e a k ~ F o r w a r d ~ S u r g e ~ C u r r e n t ~}$ | 500 mAdc |

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

THERMAL CHARACTERISTICS

| Parameter | Symbol | Max. | Unit |
| :--- | :---: | :---: | :---: |
| Total Device Dissipation FR-5 BoardNOTE1 |  |  |  |
| $@ \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | PD | 200 | mW |
| Derate above $25^{\circ} \mathrm{C}$ |  | 1.57 | $\mathrm{~mW} /{ }^{\circ} \mathrm{C}$ |
| Thermal Resistance Junction to Ambient | $\mathrm{R}_{\text {өJA }}$ | 635 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction and Storage Temperature | $\mathrm{T}_{\mathrm{J}, \mathrm{T}} \mathrm{T}_{\mathrm{STG}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |

NOTE1: FR-4 Minimum Pad

## ELECTRICAL CHARACTERISTICS

$\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, unless otherwise noted

| Parameter | Symbol | Conditions | Min | Tye | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| OFF CHARACTERISTICS |  |  |  |  |  |  |
| Reverse Breakdown Voltage | $\mathrm{V}_{\text {(BR) }}$ | $\mathrm{I}_{\mathrm{BR}}=100 \mu \mathrm{Adc}$ | 70 |  |  | Vdc |
| Reverse Voltage Leakage Current | $\mathrm{I}_{\mathrm{R}}$ | $\mathrm{V}_{\mathrm{R}}=50 \mathrm{Vdc}$ |  |  | 1.0 | uAdc |
| Forward Voltage | $V_{F}$ | $\mathrm{I}_{\mathrm{F}}=1.0 \mathrm{mAdc}$ |  | 0.55 | 0.7 | Vdc |
|  |  | $\mathrm{I}_{\mathrm{F}}=100 \mathrm{mAdc}$ |  | 0.85 | 1.1 |  |
| Reverse Recovery Time | $t_{\text {rr }}$ | $\begin{aligned} & I_{F}=I_{R}=10 \mathrm{mAdc} \\ & I_{R(R E C)}=1.0 \mathrm{mAdc}(\text { Figure } 1) \end{aligned}$ |  |  | 4.0 | ns |
| Capacitance | C | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}$ |  |  | 2.5 | pF |

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## TEST CIRCUIT

Figure 1. Recovery Time Equivalent Test Circuit


NOTE1: A $2.0 \mathrm{k} \Omega$ variable resistor adjusted for a Forward Current ( $\mathrm{I}_{\mathrm{F}}$ ) of 10 mA .
NOTE2: Input pulse is adjusted so $\mathrm{I}_{\mathrm{R}(\text { peak })}$ is equal to 10 mA .
NOTE3: $t_{p}$ » $t_{r}$

## TYPICAL CHARACTERISTICS

1. Forward Voltage

2. Capacitance

$\mathrm{V}_{\mathrm{R}}$, REVERSE VOLTAGE (VOLTS)
3. Leakage Current


## PACKAGE INFORMATION

Dimension in SOD-323 Package (Unit: mm)


## SOLDERING FOOTPRINT*



| DIM | MILLIMETERS |  | INCHES |  |
| :---: | :---: | :---: | :---: | :---: |
|  | MIN | MAX | MIN | MAX |
| A | 0.80 | 1.00 | 0.031 | 0.040 |
| A1 | 0.00 | 0.10 | 0.000 | 0.004 |
| A3 | 0.15 REF |  | 0.006 REF |  |
| b | 0.25 | 0.40 | 0.010 | 0.016 |
| C | 0.089 | 0.177 | 0.003 | 0.007 |
| D | 1.60 | 1.80 | 0.062 | 0.070 |
| E | 1.15 | 1.35 | 0.045 | 0.053 |
| L | 0.08 |  | 0.003 |  |
| HE | 2.30 | 2.70 | 0.090 | 0.105 |

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